FIG. 1

FIG. 2 (a)

SILICON

⇩ LAYER THICKNESS
REDUCTION BY CURE

FIG. 2 (b)

SILICON

FIG.3

MESH

EMULSION-COATED
OR PLATED MASK

Cu POST

SILICON

FIRST
PRINTING →

SOLID MATTER
CONTENT : 45%

CURE →

FIG.4

SOLID MATTER
CONTENT : 45%

FIRST
PRINTING

CURE

SILICON

FIG.5

METAL MASK

SILICON

CURE
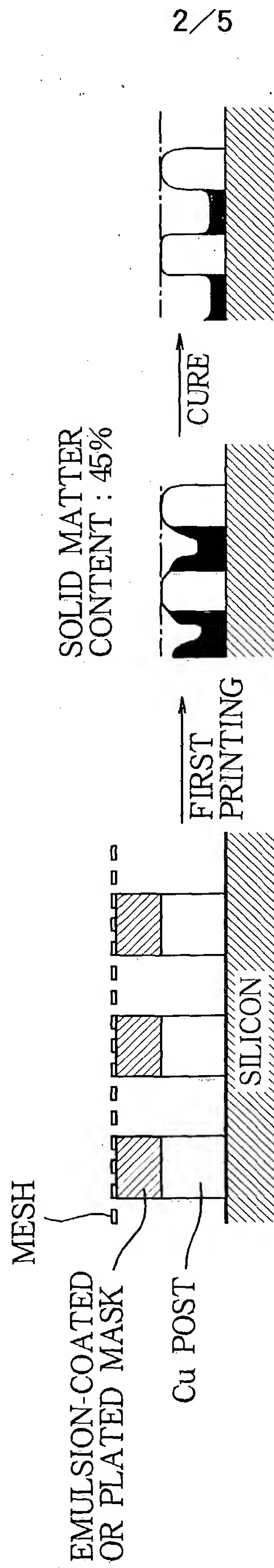
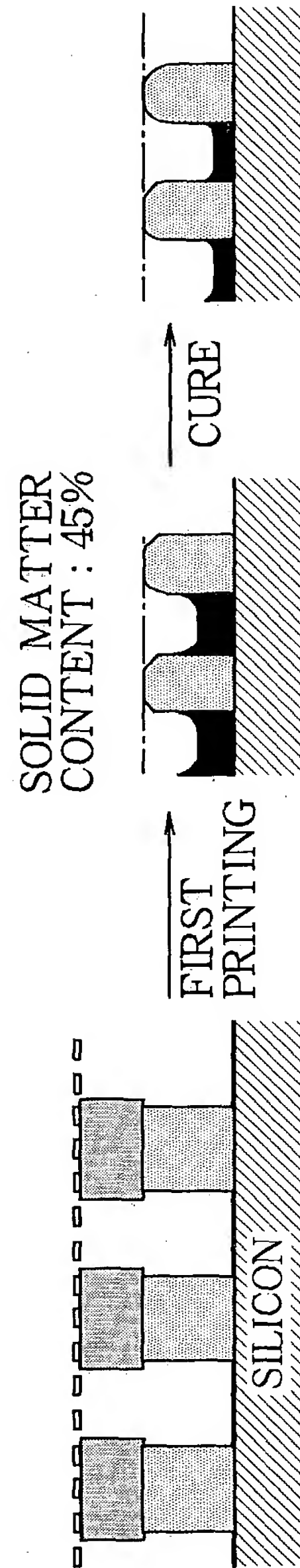CURE

SOLID MATTER CONTENT : 14%

SOLID MATTER CONTENT : 26%
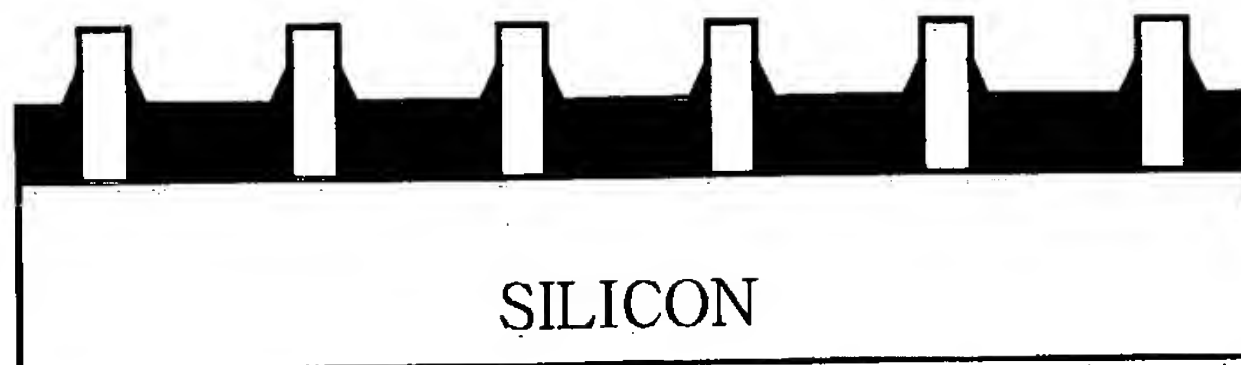
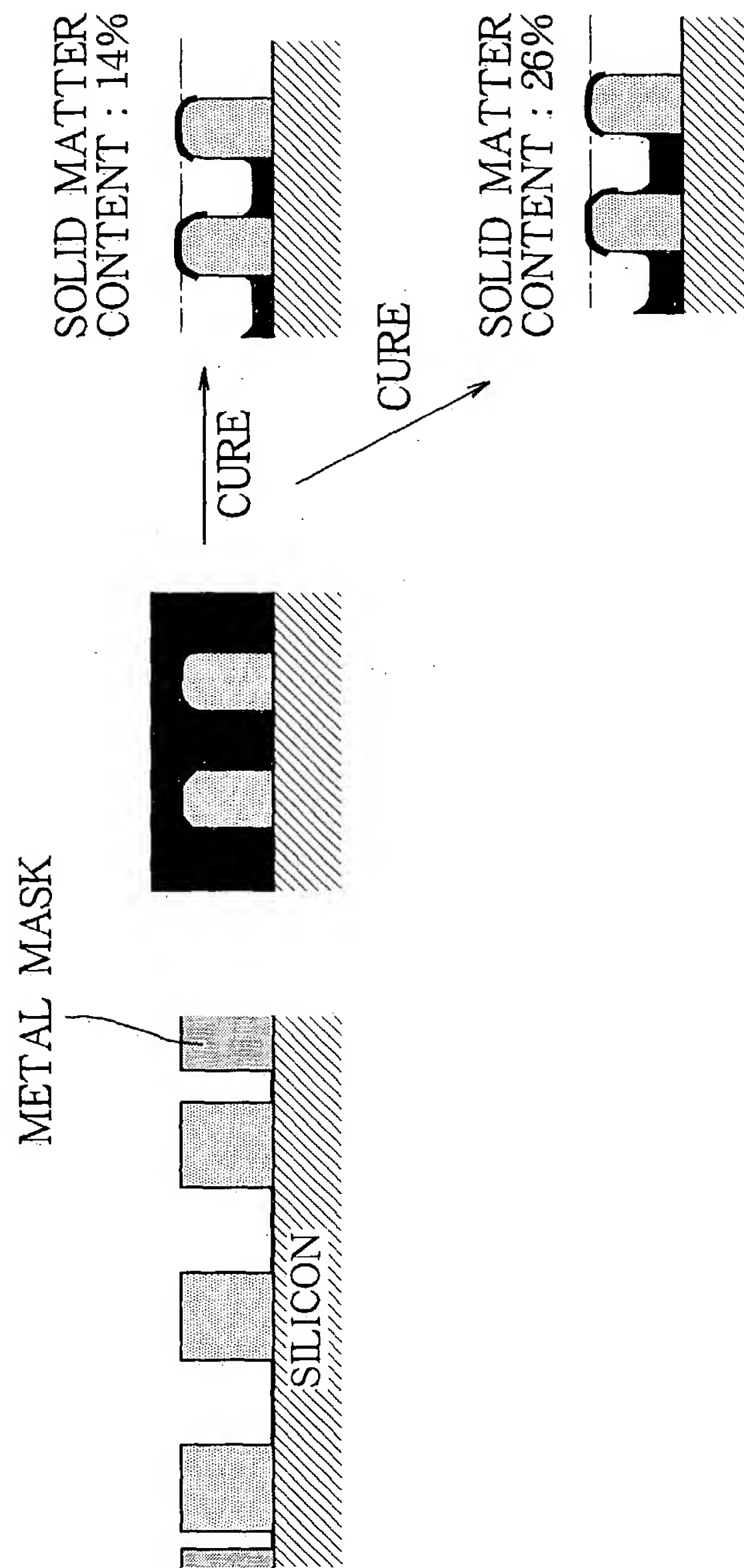# FIG.6

MATERIAL	YOUNG'S MODULUS	POISSON'S RATIO	MASS DENSITY	INSTANTANEOSU LINEAR EXPANSION COEFFICIENT	EQUIV. (Von Misers) TNESIL YIELD STRESS	EQUIV. 10 cycles TNESIL YIELD STRESS
	Mpa		g/mm³	ppm		
HIGH-ELASTIC RESIN	2.15600+4	0.24000+0	1.95000+3	8.50000−6	1.09900+1	0.00000+0
LOW-ELASTIC RESIN	1.20000+3	0.30000+0	1.86000+3	1.40000−5	0.00000+0	0.00000+0
Si	1.70000+5	0.26000+0	2.32800+3	2.60000−6	0.00000+0	0.00000+0
Sn-Pb (63 : 37)	2.46760+4	0.33000+0	8.30000+3	2.40000−5	4.06590+1	0.00000+0
FR-4	1.85710+4	2.50000+0	1.85000+3	1.50000−5	0.00000+0	0.00000+0
Cu	1.30000+4	0.29000+0	8.93000+3	1.65000−5	0.00000+0	0.00000+0
POLYIMIDE	3.80000+4	0.25000+0	1.85000+3	2.00000−5	0.00000+0	0.00000+0

TEMPERATURE DEPENDENCE
OF INSTANTANEOUS LINEAR
EXPANSION COEFFICIENT OF
LOW-ELASTIC RESIN

TEMPERATUREE	INSTANTANEOUS LINEAR EXPANSION COEFFICIENT
−25℃	1.40000−05
19.9999℃	1.40000−05
20℃	7.00000−05
125℃	7.00000−05

TEMPERATURE DEPENDENCE
OF Sn-Pb (63 : 37) SOLDER

TEMPERATURE	YIELD STREES	YOUNG'S MODULUS	WORK HARDENING COEFFICIENT
−65℃	4.065900+01	2.467600+04	1.000000+00
20℃	2.776712+01	2.215804+04	0.895200+00
50℃	2.181702+01	1.309339+04	4.065900+00
100℃	1.289188+01	5.539510+04	0.252390+00
150℃	3.966732+00	3.021551+03	0.128789+00